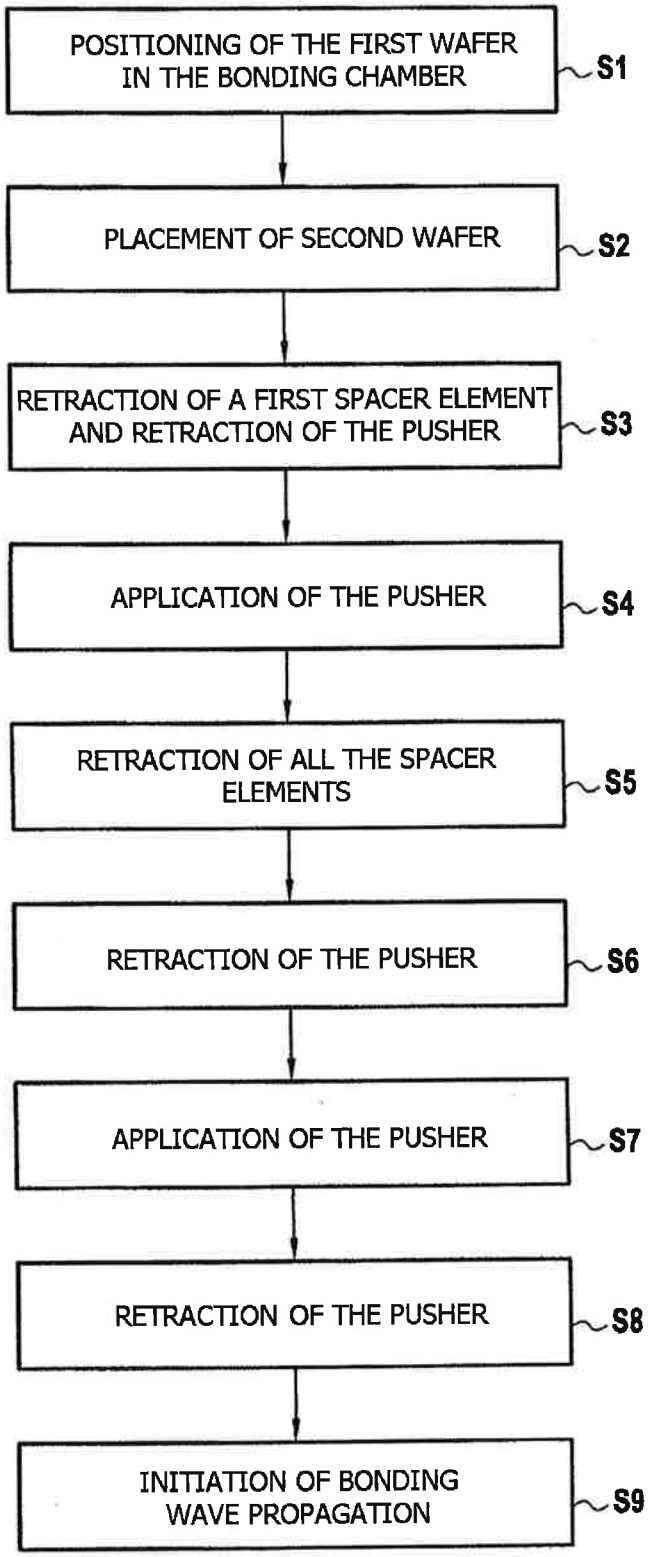

POSITIONING OF THE FIRST WAFER IN THE BONDING CHAMBER
S1
PLACEMENT OF SECOND WAFER
S2
RETRACTION OF A FIRST SPACER ELEMENT AND RETRACTION OF THE PUSHER
S3
APPLICATION OF THE PUSHER
S4
RETRACTION OF ALL THE SPACER ELEMENTS
S5
RETRACTION OF THE PUSHER
S6
APPLICATION OF THE PUSHER
S7
RETRACTION OF THE PUSHER
S8
INITIATION OF BONDING WAVE PROPAGATION
S9

FIG.1

FIG.2A

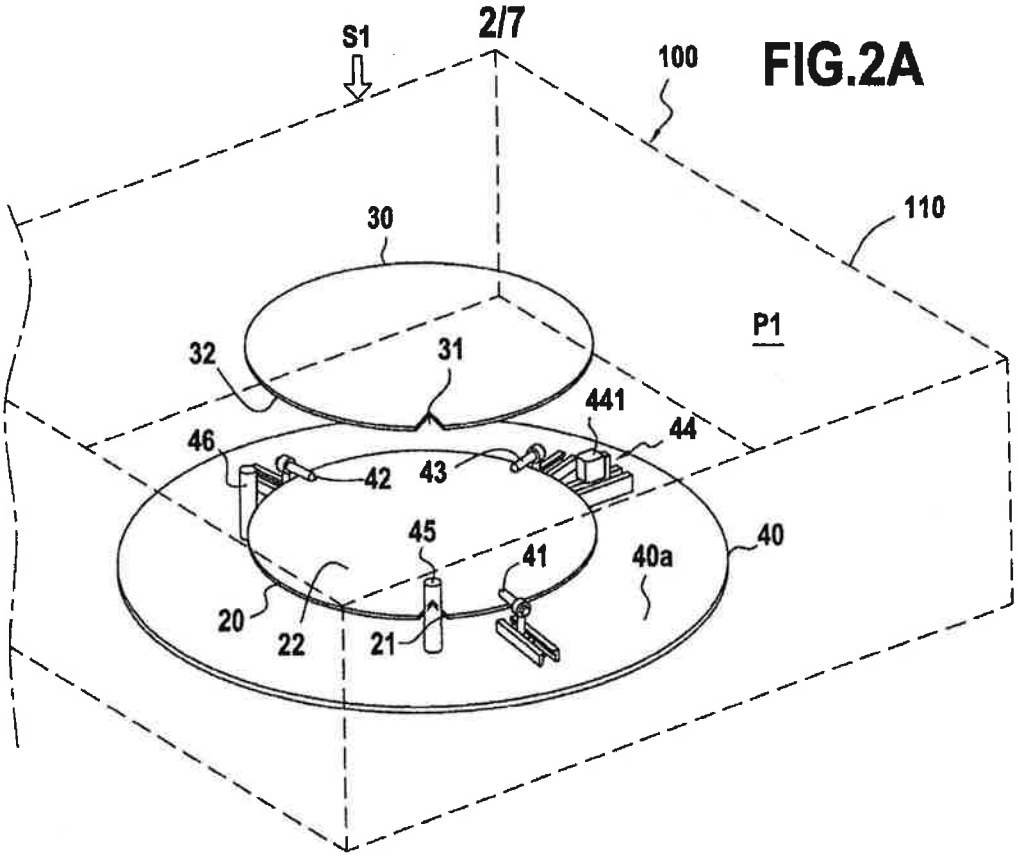
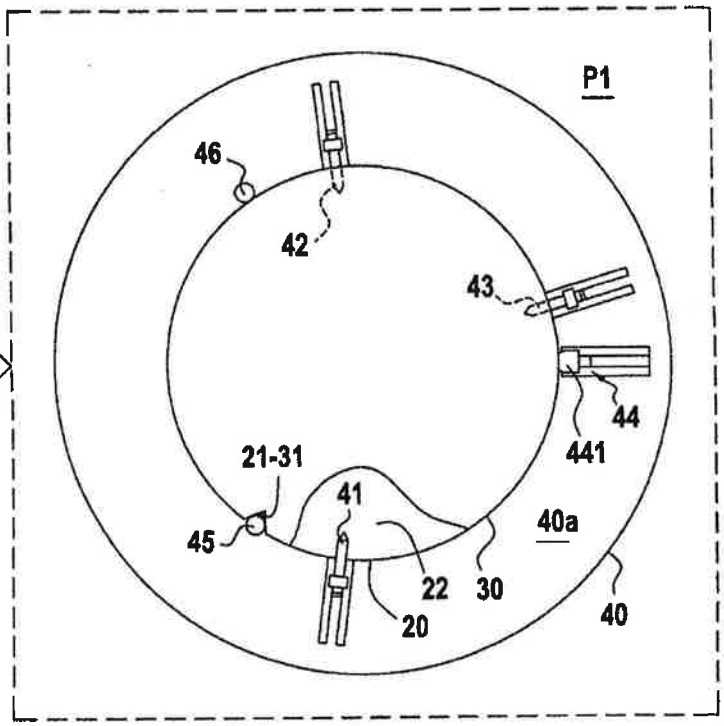

S1
100
110
30
P1
32
31
441
44
46
42
43
45
41
40a
40
20
22
21

FIG.2B


P1
46
42
43
S2
44
441
21-31
41
45
40a
22
30
20
40

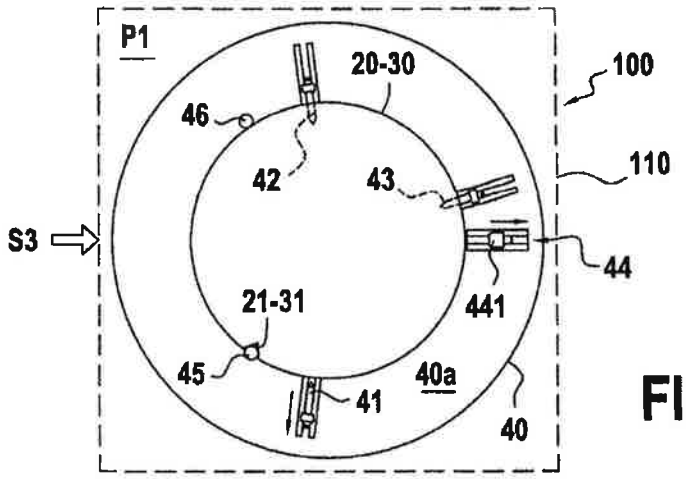


FIG.2C

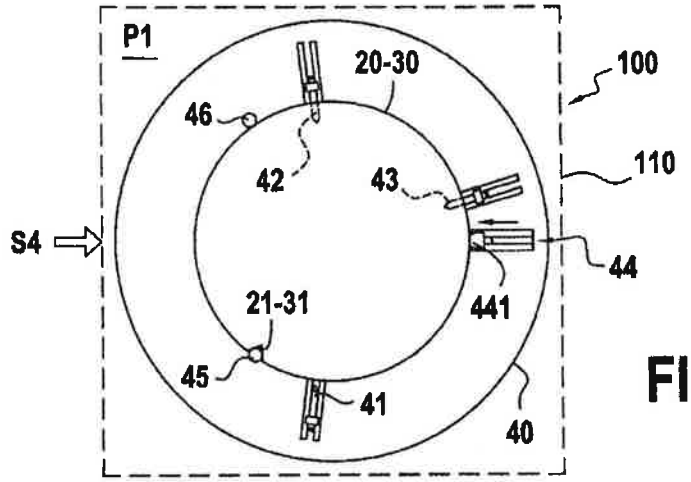


FIG.2D

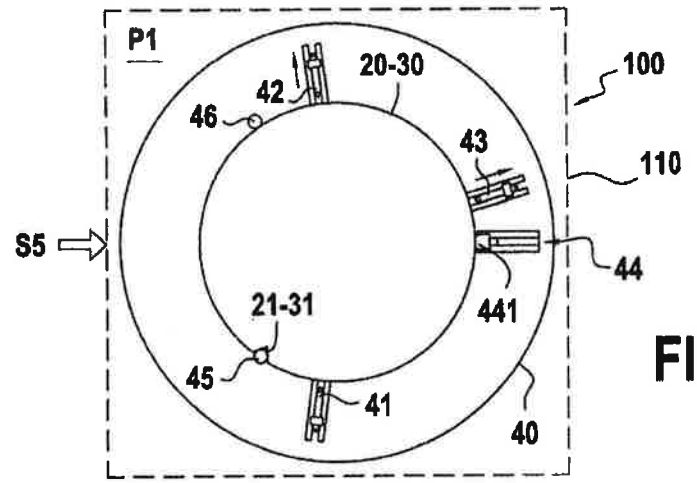


FIG.2E

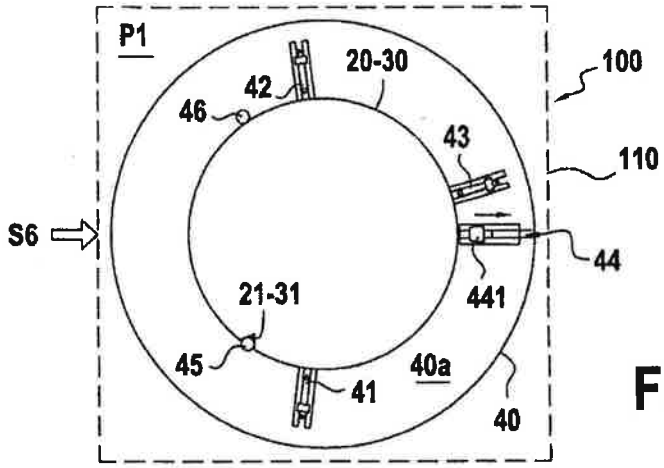


FIG.2F

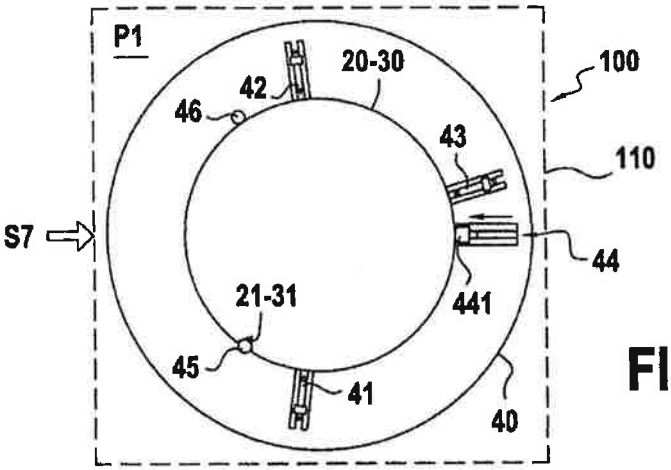


FIG.2G

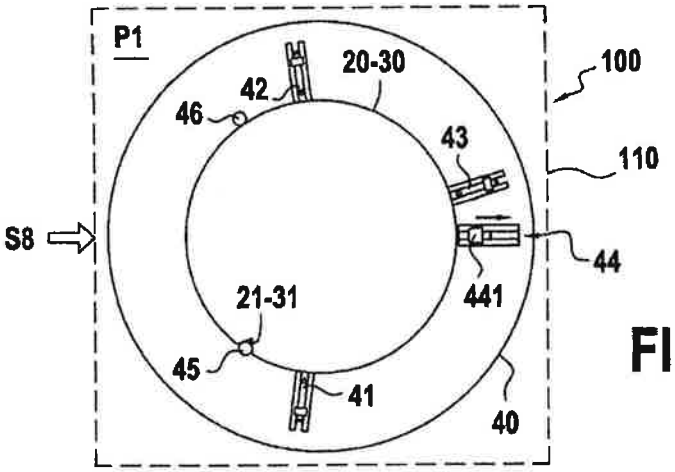


FIG.2H

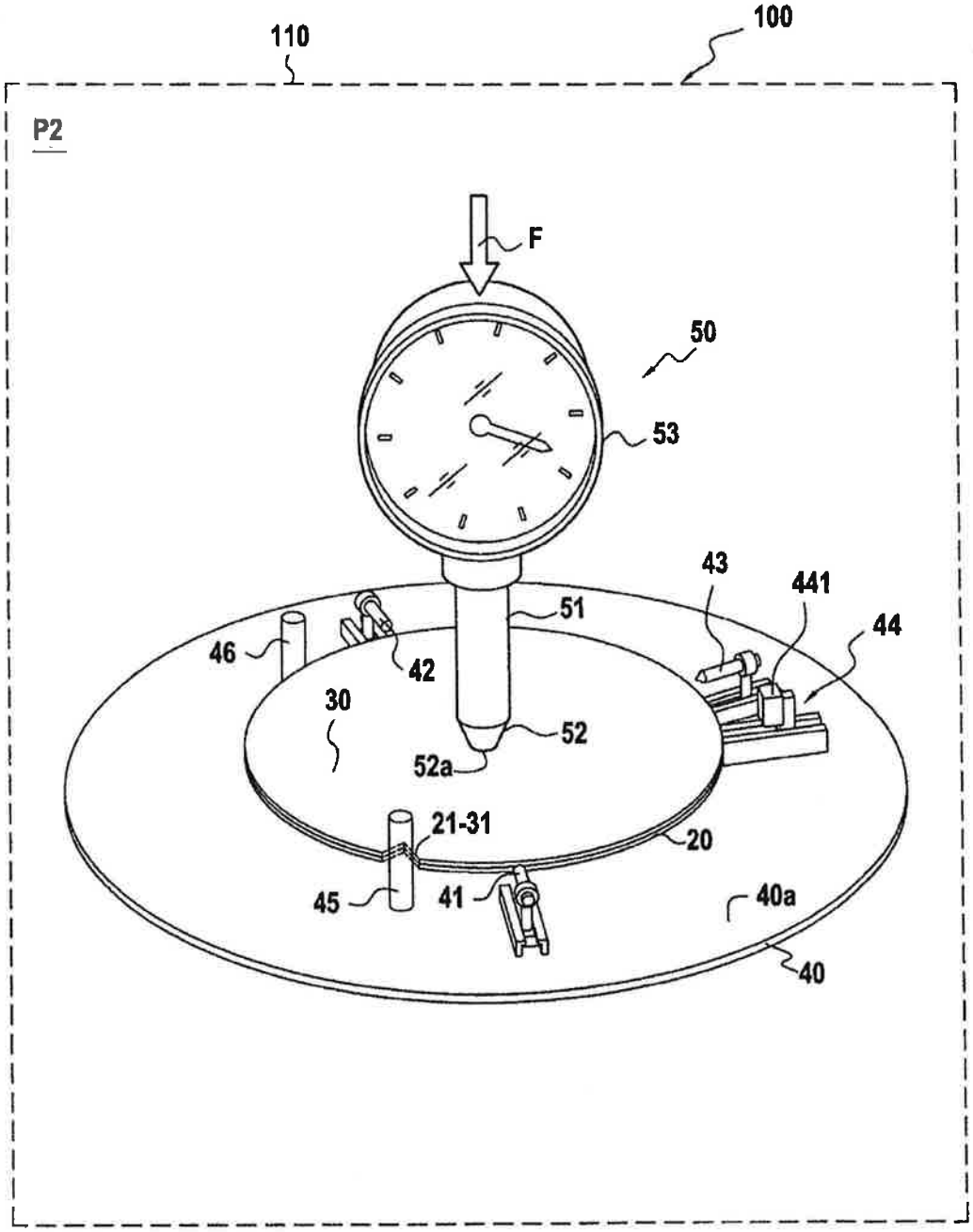


FIG.2I

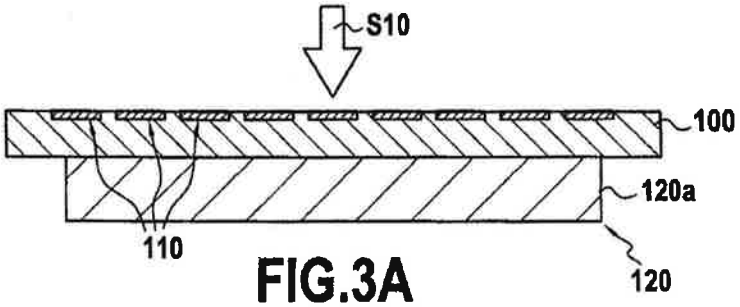


FIG.3A

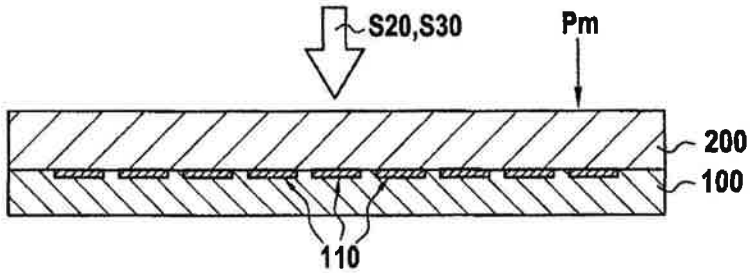


FIG.3B

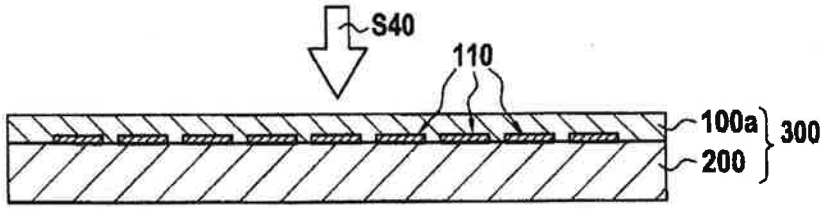


FIG.3C

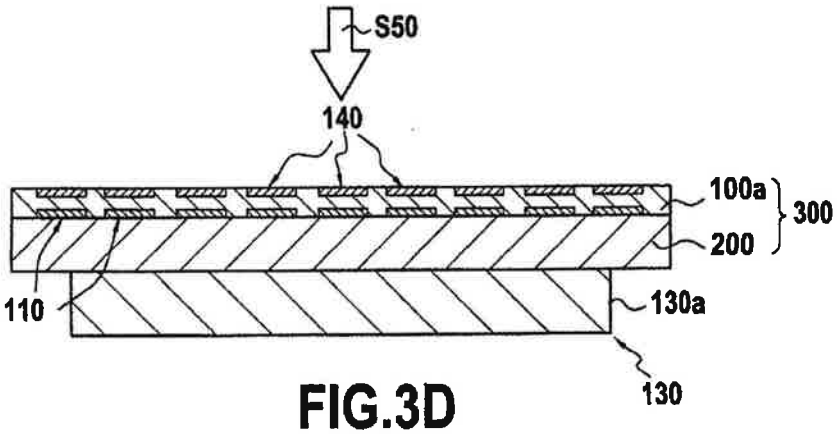


FIG.3D

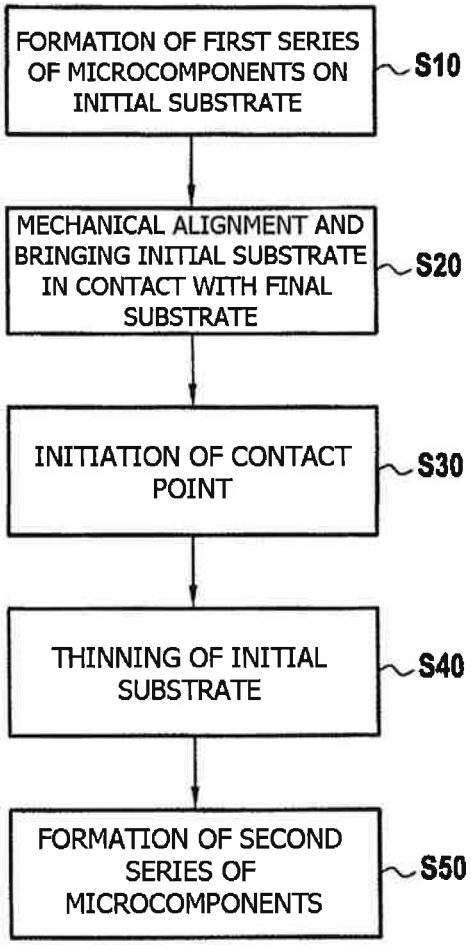

FORMATION OF FIRST SERIES OF MICROCOMPONENTS ON INITIAL SUBSTRATE
S10
MECHANICAL ALIGNMENT AND BRINGING INITIAL SUBSTRATE IN CONTACT WITH FINAL SUBSTRATE
S20
INITIATION OF CONTACT POINT
S30
THINNING OF INITIAL SUBSTRATE
S40
FORMATION OF SECOND SERIES OF MICROCOMPONENTS
S50

FIG.4

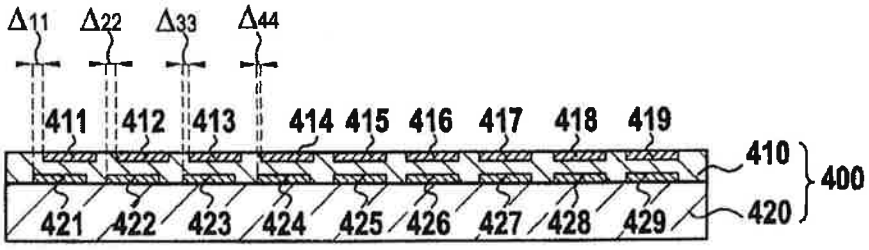

Δ11
Δ22
Δ33
Δ44
411
412
413
414
415
416
417
418
419
410
400
420
421
422
423
424
425
426
427
428
429

FIG.5